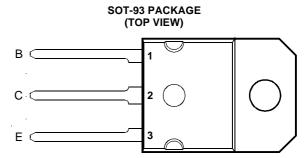
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JUNE 1973 - REVISED MARCH 1997

- **Designed for Complementary Use with the BD546 Series**
- 85 W at 25°C Case Temperature
- 15 A Continuous Collector Current
- **Customer-Specified Selections Available**



Pin 2 is in electrical contact with the mounting base.

MDTRAA

#### absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT		
	BD545		40		
Collector-base voltage (I <sub>E</sub> = 0)	BD545A	\/	60	V	
	BD545B	V <sub>CBO</sub>	80	V	
	BD545C		100		
	BD545		40		
Collector emitter voltage (L = 0) (see Note 1)	BD545A	\/	60	V	
Collector-emitter voltage (I <sub>B</sub> = 0) (see Note 1)	BD545B	V <sub>CEO</sub>	80		
	BD545C		100		
Emitter-base voltage	V <sub>EBO</sub>	5	V		
Continuous collector current	I <sub>C</sub>	15	Α		
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)			85	W	
Continuous device dissipation at (or below) 25°C free air temperature (see Note 3)			3.5	W	
Operating free air temperature range			-65 to +150	°C	
Operating junction temperature range	Tj	-65 to +150	°C		
Storage temperature range	T <sub>stg</sub>	-65 to +150	°C		
Lead temperature 3.2 mm from case for 10 seconds	TL	260	°C		

NOTES: 1. These values apply when the base-emitter diode is open circuited.

- 2. Derate linearly to 150°C case temperature at the rate of 0.68 W/°C.
- 3. Derate linearly to 150°C free air temperature at the rate of 28 mW/°C.

#### PRODUCT INFORMATION





JUNE 1973 - REVISED MARCH 1997

### electrical characteristics at 25°C case temperature

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT	
V(DD)OFO	Collector-emitter  (BR)CEO breakdown voltage	I <sub>C</sub> = 30 mA	I <sub>B</sub> = 0	BD545 BD545A	40 60			V	
(BR)CEO		breakdown voltage (see Note 4)	J	BD545B BD545C	80 100			v	
		V <sub>CE</sub> = 40 V	$V_{BE} = 0$	BD545			0.4		
I <sub>CES</sub>	Collector-emitter	$V_{CE} = 60 V$	$V_{BE} = 0$	BD545A			0.4	mΑ	
CES	cut-off current	$V_{CE} = 80 V$	$V_{BE} = 0$	BD545B			0.4	III/A	
		V <sub>CE</sub> = 100 V	$V_{BE} = 0$	BD545C			0.4		
I <sub>CEO</sub>	Collector cut-off	V <sub>CE</sub> = 30 V	I <sub>B</sub> = 0	BD545/545A			0.7	mA	
ICEO	current	$V_{CE} = 60 V$	$I_B = 0$	BD545B/545C			0.7		
I <sub>EBO</sub>	Emitter cut-off current	V <sub>EB</sub> = 5 V	I <sub>C</sub> = 0				1	mA	
	Forward current transfer ratio	$V_{CE} = 4 V$		$I_C = 1 A$ $I_C = 5 A$ (see Notes 4 and 5)	60				
h <sub>FE</sub>		$V_{CE} = 4 V$	$I_C = 5 A$		25				
	transfer ratio	$V_{CE} = 4 V$	$I_C = 10 A$		10				
V <sub>CE(sat)</sub>	Collector-emitter	$I_B = 625 \text{ mA}$	$I_C = 5 A$	(see Notes 4 and 5)			0.8	V	
*CE(sat)	saturation voltage	$I_B = 2 A$	$I_C = 10 A$				1	•	
V <sub>BE</sub>	Base-emitter	V <sub>CE</sub> = 4 V	I <sub>C</sub> = 10 A	(see Notes 4 and 5)			1.8	V	
*BE	voltage						1.0	v	
h <sub>fe</sub>	Small signal forward	V <sub>CE</sub> = 10 V	Vo= = 10 V	I <sub>C</sub> = 0.5 A	f = 1 kHz	20			
' 'fe	current transfer ratio	VCE - 10 V	1C = 0.5 A	1 - 1 10 12	20				
h <sub>fe</sub>	Small signal forward current transfer ratio	V <sub>CE</sub> = 10 V	I <sub>C</sub> = 0.5 A	f = 1 MHz	3				

NOTES: 4. These parameters must be measured using pulse techniques,  $t_p$  = 300  $\mu$ s, duty cycle  $\leq$  2%.

#### thermal characteristics

	PARAMETER				UNIT
$R_{\theta JC}$	Junction to case thermal resistance			1.47	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			35.7	°C/W

### resistive-load-switching characteristics at 25°C case temperature

	PARAMETER	TEST CONDITIONS †			MIN	TYP	MAX	UNIT
t <sub>on</sub>	Turn-on time	I <sub>C</sub> = 6 A	$I_{B(on)} = 0.6 A$	$I_{B(off)} = -0.6 A$		0.6		μs
t <sub>off</sub>	Turn-off time	$V_{BE(off)} = -4 V$	$R_L = 5 \Omega$	$t_p = 20 \ \mu s, \ dc \le 2\%$		1		μs

 $<sup>^{\</sup>dagger} \ \ \mbox{Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.}$ 

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<sup>5.</sup> These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

JUNE 1973 - REVISED MARCH 1997

#### TYPICAL CHARACTERISTICS

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Figure 1.

### **COLLECTOR-EMITTER SATURATION VOLTAGE**

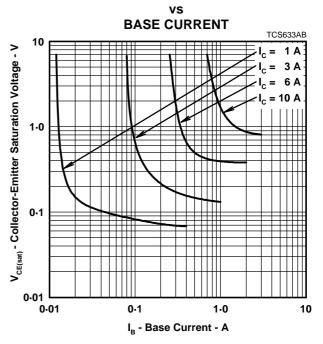
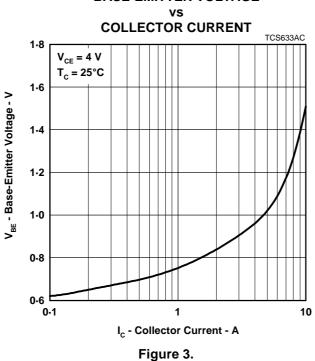


Figure 2.

#### **BASE-EMITTER VOLTAGE**

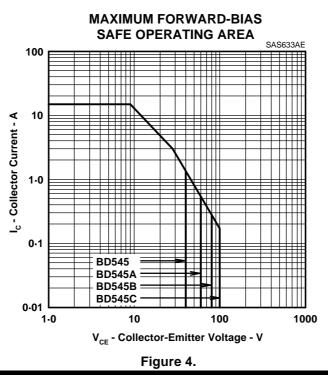


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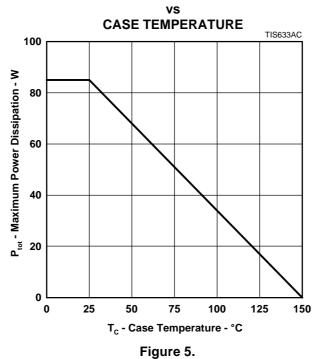
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#### **MAXIMUM SAFE OPERATING REGIONS**



#### THERMAL INFORMATION

#### **MAXIMUM POWER DISSIPATION**



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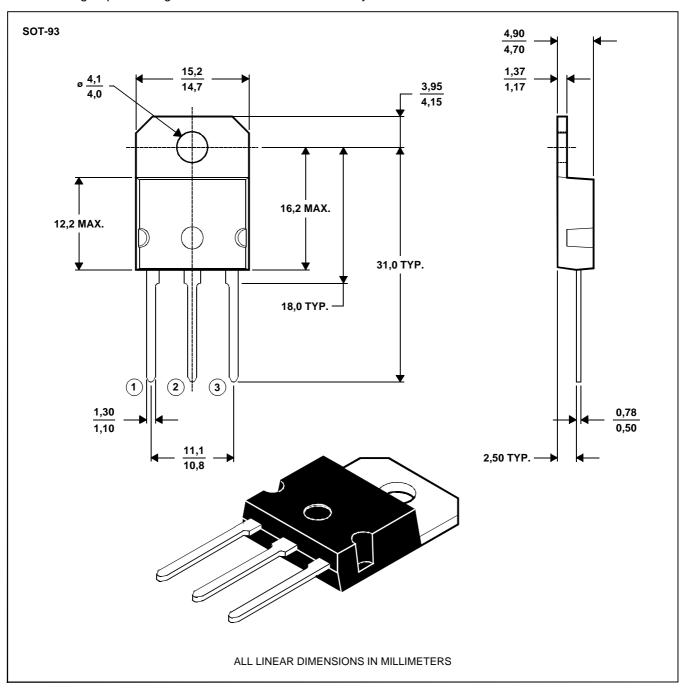
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#### **MECHANICAL DATA**

#### **SOT-93**

#### 3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.

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JUNE 1973 - REVISED MARCH 1997

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